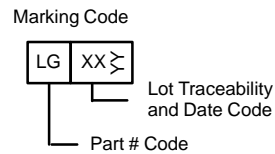
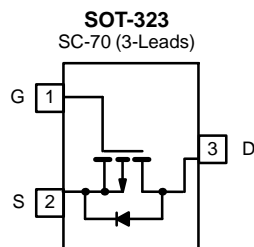


P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (mA)
-20	3.8 @ $V_{GS} = -4.5$ V	-180
	5.0 @ $V_{GS} = -2.5$ V	-100



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 8	
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	I_D	$T_A = 25^\circ\text{C}$	-180
		$T_A = 70^\circ\text{C}$	-140
Pulsed Drain Current	I_{DM}	-500	mA
Maximum Power Dissipation ^a	P_D	$T_A = 25^\circ\text{C}$	0.15
		$T_A = 70^\circ\text{C}$	0.10
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Maximum Junction-to-Ambient ^a	R_{thJA}	833	$^\circ\text{C/W}$

Notes

a. Surface Mounted on FR4 Board, $t \leq 10$ sec.



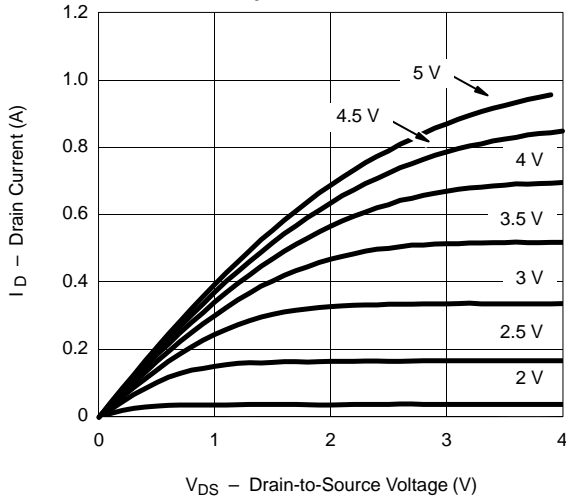
SPECIFICATIONS (T _J = 25 °C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{DS} = 0 V, I _D = -10 μA	-20	-24		V
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -50 μA	-0.4	-0.9	-1.5	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±8 V		±2	±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V		-0.001	-100	
		V _{DS} = -20 V, V _{GS} = 0 V, T _J = 55 °C			-1	μA
On-State Drain Current ^a	I _{D(on)}	V _{GS} ≥ -4.5 V, V _{DS} = -8.0 V	-400			mA
		V _{GS} ≥ -2.5 V, V _{DS} = -5.0 V	-120			
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = -4.5 V, I _D = -180 mA		2.6	3.8	Ω
		V _{GS} = -2.5 V, I _D = -75 mA		4.0	5.0	
Forward Transconductance ^a	g _{fs}	V _{DS} = -2.5 V, I _D = -50 mA		200		mS
Diode Forward Voltage ^a	V _{SD}	I _S = -50 mA, V _{GS} = 0 V		-0.7	-1.2	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} = -5.0 V, V _{GS} = -4.5 V, I _D = -100 mA		350	450	pC
Gate-Source Charge	Q _{gs}			25		
Gate-Drain Charge	Q _{gd}			125		
Input Capacitance	C _{iss}	V _{DS} = -5.0 V, V _{GS} = 0 V, f = 1 MHz		20		pF
Output Capacitance	C _{oss}			14		
Reverse Transfer Capacitance	C _{rss}			5		
Switching^{b, c}						
Turn-On Delay Time	t _{d(on)}	V _{DD} = -3.0 V, R _L = 100 Ω I _D = -0.25 A, V _{GEN} = -4.5 V, R _G = 10 Ω		7	12	ns
Rise Time	t _r			25	35	
Turn-Off Delay Time	t _{d(off)}			19	30	
Fall Time	t _f			9	15	

Notes

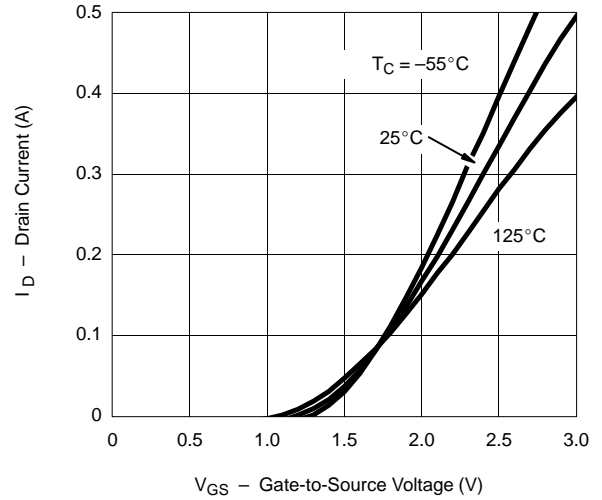
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
b. For design only, not subject to production testing.
c. Switching time is essentially independent of operating temperature.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

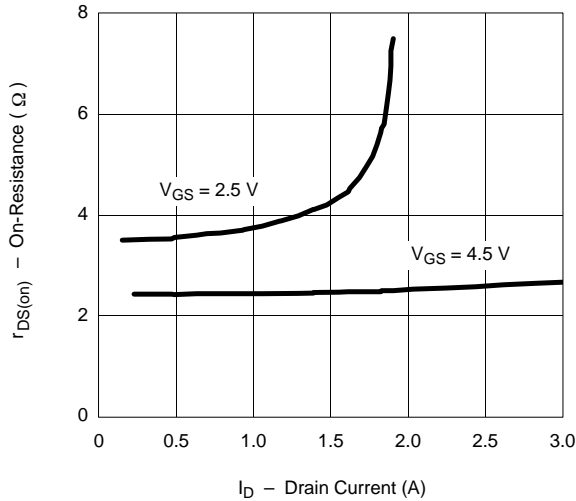
Output Characteristics



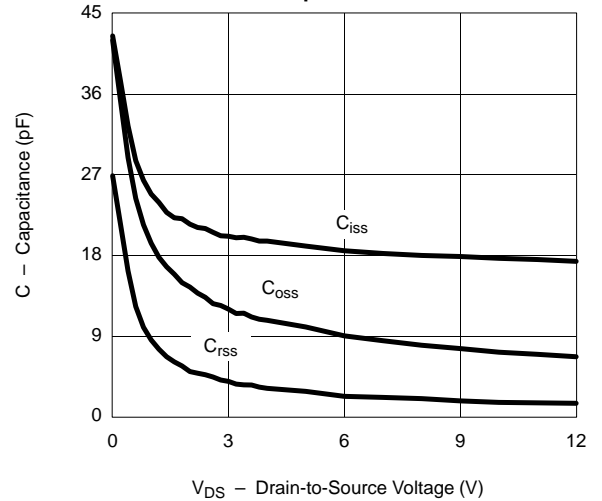
Transfer Characteristics



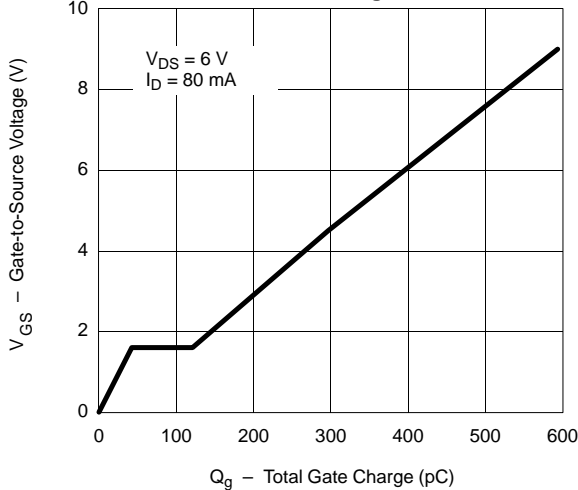
On-Resistance vs. Drain Current



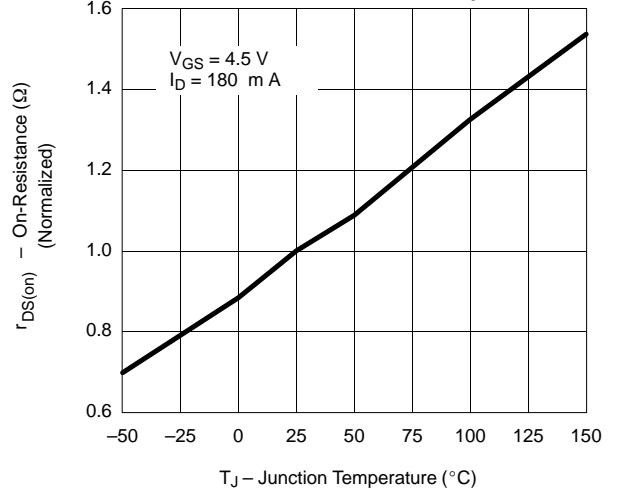
Capacitance



Gate Charge



On-Resistance vs. Junction Temperature





TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

